

<b>Notice of References Cited</b>		Application N.	Applicant(s)
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		Examiner	Group Art Unit
		George Goudrean	1763
		Pag 1 of 1	

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*	DOCUMENT NO.	DATE	NAME	CLASS	SUBCLASS
A	6436812	8-20-02	See	438	636
B	2002/0132488	9-19-02	Nolan	438	720
C					
D					
E					
F					
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N	61-171,127	8-1-86	Japan	Yoshichika et al		
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NON-PATENT DOCUMENTS

*	DOCUMENT (Including Author, Title, Source, and Pertinent Pages)	DATE
U	"Implementation of Tungsten Metallization In Multilevel Interconnection Technologies"; IEEE Trans, On Semiconductor Mfg.; vol. 3 no. 4; (11-1990); Riley et al.; pp. 150-157	
W	"X-Ray mask Fabrication Technology For 0.5um Very Large Scale Integrated Circuits"; J. Vac. Sci.; B; 14(6); (12-1996); Oda et.al.; pp.4366-4370	
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\* A copy of this reference is not being furnished with this Office action.  
(See Manual of Patent Examining Procedure, Section 707.05(a).)